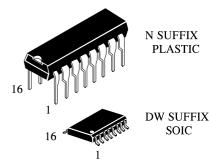
### **ANALOG MULTIPLEXER DEMULTIPLEXER** High-Performance Silicon-Gate CMOS

The IN74HC4051 utilize silicon-gate CMOS technology to achieve fast propagation delays, low ON resistances, and low OFF leakage currents. These analog multiplexers/demultiplexers control analog voltages that may vary across the complete power supply range (from  $V_{CC}$  to  $V_{EE}$ ).

The Channel-Select inputs determine which one of the Analog Inputs/Outputs is to be connected, by means of an analog switch, to the Common Output/Input.When the Enable pin is high, all analog switches are turned off.

The Channel-Select and Enable inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LS/ALSTTL outputs.

- Fast Switching and Propagation Speeds
- Low Crosstalk Between Switches
- Diode Protection on All Inputs/Outputs
- Analog Power Supply Range (V<sub>CC</sub>-V<sub>EE</sub>)=2.0 to 12.0 V
- Digital (Control) Power Supply Range (V<sub>CC</sub>-GND)=2.0 to 6.0 V
- Low Noise



#### ORDERING INFORMATION

IN74HC4051N Plastic IN74HC4051DW SOIC  $T_A = -55^{\circ}$  to 125° C for all

packages
PIN ASSIGNMENT

1 ●	16	v <sub>cc</sub>
2	15	X2
3	14	<b>X</b> 1
4	13	x0
5	12	] X3
6	11	ЪА
7	10	В
8	9	рс
	2 3 4 5 6 7	2 15 3 14 4 13 5 12 6 11 7 10

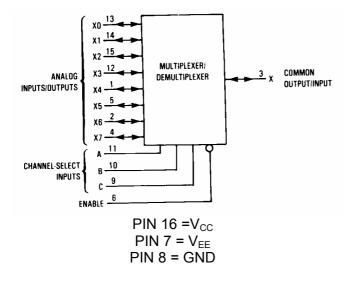
#### **FUNCTION TABLE**

Co	Control Inputs				
Enable	Select		Channels		
	С	В	Α		
L	L	L	L	X0	
L			Η	X1	
L	L	Н	L	X2	
L		H	Η	X3	
L	H		L	X4	
L	Н	L	Н	X5	
L	H	H	L	X6	
L	Н	Н	Н	X7	
Н	Х	Х	Х	None	
$V = do n^{2}$					

X = don't care



### LOGIC DIAGRAM Single-Pole, 8-Position Plus Common Off



### MAXIMUM RATINGS<sup>\*</sup>

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	Positive DC Supply Voltage (Referenced to GND)	-0.5 to +7.0 -0.5 to +14.0	V
	(Referenced to V <sub>EE</sub> )		
$V_{\text{EE}}$	Negative DC Supply Voltage (Referenced to GND)	-7.0 to +0.5	V
$V_{IS}$	Analog Input Voltage	V <sub>EE</sub> - 0.5 to V <sub>CC</sub> +0.5	V
V <sub>IN</sub>	Digital Input Voltage (Referenced to GND)	-1.5 to V <sub>CC</sub> +1.5	V
I	DC Input Current Into or Out of Any Pin	±25	mA
P <sub>D</sub>	Power Dissipation in Still Air, Plastic DIP+ SOIC Package+	750 500	mW
Tstg	Storage Temperature	-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds (Plastic DIP or SOIC Package)	260	°C

<sup>\*</sup>Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions. +Derating - Plastic DIP: - 10 mW/°C from 65° to 125°C

Ig - Plastic DIP: - 10 mW/ $^{\circ}$ C from 65° to 125°C

SOIC Package: : - 7 mW/°C from 65° to 125°C

### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Min	Max	Unit
V <sub>CC</sub>	Positive Supply Voltage (Referenced to GND)	2.0	6.0	V
	(Referenced to $V_{EE}$ )	2.0	12.0	
V <sub>EE</sub>	Negative DC Supply Voltage (Referenced to GND)	- 6.0	GND	V
V <sub>IS</sub>	Analog Input Voltage	V <sub>EE</sub>	V <sub>CC</sub>	V
V <sub>IN</sub>	Digital Input Voltage (Referenced to GND)	GND	V <sub>CC</sub>	V
V <sub>IO</sub> *	Static or Dynamic Voltage Across Switch	-	1.2	V
T <sub>A</sub>	Operating Temperature, All Package Types	-55	+125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time (Channel V <sub>CC</sub> =2.0 V	0	1000	ns
	Select or Enable Inputs) $V_{CC} = 4.5 V$	0	500	
	V <sub>CC</sub> =6.0 V	0	400	

<sup>\*</sup> For voltage drops across the switch greater than 1.2 V (switch on), excessive V<sub>CC</sub> current may be drawn;

i. e., the current out of the switch may contain both  $V_{CC}$  and switch input components. The reliability of the device will be unaffected unless the Maximum Ratings are exceeded.

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation,  $V_{\text{IN}}$  and  $V_{\text{OUT}}$  should be constrained to the range indicated in the Recommended Operating Conditions.

Unused digital input pins must always be tied to an appropriate logic voltage level (e.g., either GND or  $V_{CC}$ ). Unused Analog I/O pins may be left open or terminated.



### IN74HC4051

# **DC ELECTRICAL CHARACTERISTICS** Digital Section (Voltages Referenced to GND) $V_{EE}$ =GND, Except Where Noted

			V <sub>CC</sub>	Guara	anteed L	imit	
Symbol	Parameter	Test Conditions	V	25 °C to	≤85	≤125	Unit
				-55°C	°C	°C	
V <sub>IH</sub>	Minimum High-Level	R <sub>on</sub> = Per Spec	2.0	1.5	1.5	1.5	V
	Input Voltage,		4.5	3.15	3.15	3.15	
	Channel-Select or		6.0	4.2	4.2	4.2	
	Enable Inputs						
VIL	Maximum Low -Level	R <sub>ON</sub> = Per Spec	2.0	0.3	0.3	0.3	V
	Input Voltage,		4.5	0.9	0.9	0.9	
	Channel-Select or		6.0	1.2	1.2	1.2	
	Enable Inputs						
I <sub>IN</sub>	Maximum Input	V <sub>IN</sub> =V <sub>CC</sub> or GND,	6.0	±0.1	±1.0	±1.0	μA
	Leakage Current,	V <sub>EE</sub> =-6.0 V					
	Channel-Select or						
	Enable Inputs						
I <sub>CC</sub>	Maximum Quiescent	Channel Select = V <sub>CC</sub> or GND					μA
	Supply Current (per	Enable = V <sub>CC</sub> or GND					
	Package)	$V_{IS} = V_{CC}$ or GND					
		$V_{IO}$ = 0 V $V_{EE}$ = GND	6.0	2	20	40	
		V <sub>EE</sub> = - 6.0	6.0	8	80	160	

### DC ELECTRICAL CHARACTERISTICS Analog Section

			V <sub>CC</sub>	$V_{\text{EE}}$	Guara	anteed	Limit	
Symbol	Parameter	Test Conditions	V	V	25 °C to	≤85	≤125	Unit
					-55°C	°C	°C	
R <sub>ON</sub>	Maximum "ON"	V <sub>IN</sub> =V <sub>IL</sub> or V <sub>IH</sub>	4.5	0.0	190	240	280	Ω
	Resistance	$V_{IS} = V_{CC}$ or $V_{EE}$	4.5	-4.5	120	150	170	
		$I_{S} \le 2.0 \text{ mA}(\text{Figure 1})$	6.0	-6.0	100	125	140	
		V <sub>IN</sub> =V <sub>IL</sub> or V <sub>IH</sub>	4.5	0.0	150	190	230	
		$V_{IS} = V_{CC}$ or $V_{EE}$	4.5	-4.5	100	125	140	
		(Endpoints)						
		$I_S \le 2.0 \text{ mA}(Figure 1)$	6.0	-6.0	80	100	115	
$\Delta R_{ON}$	Maximum Difference in	V <sub>IN</sub> =V <sub>IL</sub> or V <sub>IH</sub>	4.5	0.0	30	35	40	Ω
	"ON" Resistance Between	$V_{IS} = 1/2 (V_{CC} - V_{EE})$	4.5	-4.5	12	15	18	
	Any Two Channels in the	$I_S \le 2.0 \text{ mA}$	6.0	-6.0	10	12	14	
	Same Package							
I <sub>OFF</sub>	Maximum Off- Channel	$V_{IN}=V_{IL}$ or $V_{IH}$	6.0	-6.0	0.1	0.5	1.0	μA
	Leakage Current, Any	$V_{IO} = V_{CC} - V_{EE}$						
	One Channel	Switch Off (Figure 2)						
	Maximum Off- Channel	$V_{IN}=V_{IL}$ or $V_{IH}$	6.0	-6.0	0.2	2.0	4.0	
	Leakage Current,	$V_{IO} = V_{CC} - V_{EE}$						
	Common Channel	Switch Off (Figure 3)						
I <sub>ON</sub>	Maximum On- Channel	$V_{IN}=V_{IL}$ or $V_{IH}$	6.0	-6.0	0.2	2.0	4.0	μA
	Leakage Current,	Switch to Switch =						
	Channel to Channel	$V_{CC}$ - $V_{EE}$ (Figure 4)						



## IN74HC4051

### AC ELECTRICAL CHARACTERISTICS(C<sub>L</sub>=50pF,Input t<sub>r</sub>=t<sub>f</sub>=6.0 ns)

			$V_{CC}$	Gua	ranteed l	_imit	
Symbol	Parameter	r	V	25 °C	≤85°C	≤125	Unit
				to		°C	
				-55°C			
t <sub>PLH</sub> ,	Maximum Propagation E	elay, Channel-	2.0	370	465	550	ns
t <sub>PHL</sub>	Select to Analog Output	(Figures 8 and	4.5	74	93	110	
	9)		6.0	63	79	94	
t <sub>PLH</sub> ,	Maximum Propagation [	Delay , Analog	2.0	60	75	90	ns
t <sub>PHL</sub>	Input to Analog Output (	4.5	12	15	18		
	11)	6.0	10	13	15		
t <sub>PLZ</sub> ,	Maximum Propagation De	2.0	290	364	430	ns	
t <sub>PHZ</sub>	Analog Output (Figures 12	2 and 13)	4.5	58	73	86	
			6.0	49	62	73	
t <sub>PZL</sub> ,	Maximum Propagation De		2.0	345	435	515	ns
t <sub>PZH</sub>	Analog Output (Figures 12	2 and 13)	4.5	69	87	103	
			6.0	59	74	87	
$C_{\text{IN}}$	Maximum Input Capacita	ance, Channel-	-	10	10	10	pF
	Select or Enable Inputs				0.5	~-	
C <sub>I/O</sub>	Maximum Capacitance		-	35	35	35	pF
	Analog	All Switches					
	I/O	Off				100	
	Common O/I		-	130	130	130	
	Feedthrough		-	1.0	1.0	1.0	

	Power Dissipation Capacitance (Per Package) (Figure 14)	Typical @25°C,V <sub>CC</sub> =5.0 V, V <sub>EE</sub> =0 V	
C <sub>PD</sub>	Used to determine the no-load dynamic	45	pF
	power consumption:		
	$P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$		



### IN74HC4051

ADDITIONAL	APPLICATION	CHARACTERISTICS	(GND = 0.0 V)

			$V_{CC}$	$V_{EE}$	Limit <sup>*</sup>	
Symbol	Parameter	Test Conditions	V	V	25 °C	Unit
BW	Maximum On-	f <sub>in</sub> =1 MHz Sine Wave				MHz
	Channel	Adjust f <sub>in</sub> Voltage to Obtain 0 dBm at				
	Bandwidth or	V <sub>os</sub>	2.25	-2.25	80	
	Minimum	Increase f <sub>in</sub> Frequence Until dB	4.50	-4.50	80	
	Frequency	Meter	6.00	-6.00	80	
	Response	Reads -3 dB				
	(Figure 5)	$R_L = 50 \Omega, C_L = 10 pF$				10
-	Off-Channel	f <sub>in</sub> = Sine Wave				dB
	Feedthrough	Adjust f <sub>in</sub> Voltage to Obtain 0 dBm at				
	Isolation (Figure 6)		2.25	-2.25	-50	
	(Figure 0)	$f_{in}$ = 10 kHz, R <sub>L</sub> =600 $\Omega$ , C <sub>L</sub> =50 pF	4.50	-2.25 -4.50	-50 -50	
			6.00	-6.00	-50	
		f <sub>in</sub> = 1.0 MHz, R <sub>L</sub> =50 Ω, C <sub>L</sub> =10 pF	2.25	-2.25	-40	
		$n_{\rm In} = 1.0$ m $n_{\rm Z}$ , $n_{\rm L} = 00.32$ , $0_{\rm L} = 10$ p	4.50	-4.50	-40	
			6.00	-6.00	-40	
-	Feedthrough	$V_{IN} \le 1$ Mhz Square Wave (t <sub>r</sub> = t <sub>f</sub> = 6				$mV_{P}$
	Noise,	ns)				Р
	Channel	Adjust $R_L$ at Setup so that $I_S$ = 0 A				
	Select Input to	Enable = GND	2.25	-2.25	25	
	Common O/I	R <sub>L</sub> =600 Ω, C <sub>L</sub> =50 pF	4.50	-4.50	105	
	(Figure 7)		6.00	-6.00	135	
		R <sub>L</sub> =10 Ω, C <sub>L</sub> =10 pF	2.25	-2.25	35	
			4.50	-4.50	145	
TUD	T-4-1		6.00	-6.00	190	0/
THD	Total	$f_{in}$ = 1 kHz, R <sub>L</sub> =10 kΩ, C <sub>L</sub> =50 pF				%
	Harmonic	$THD = THD_{Measured} - THD_{Source}$	2.25	2.25	0.10	
	Distortion (Figure 15)	$V_{IS}$ =4.0 $V_{PP}$ sine wave	2.25 4.50	-2.25 -4.50	0.10	
		V <sub>IS</sub> =8.0 V <sub>PP</sub> sine wave V <sub>IS</sub> =11.0 V <sub>PP</sub> sine wave	4.50 6.00	-4.50 -6.00	0.08	
			0.00	-0.00	0.00	

\* Limits not tested. Determined by design and verified by qualification.

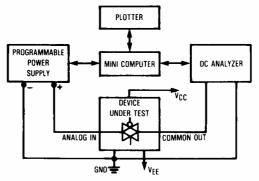


Figure 1. On Resistance Test Set-Up



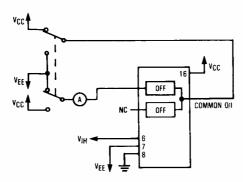


Figure 2. Maximum Off Channel Leakage Current, Any One Channel, Test Set-U<sub>P</sub>

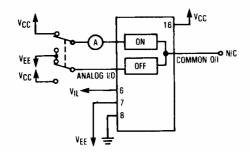
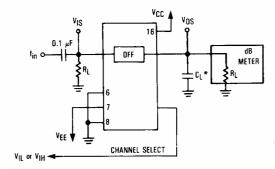


Figure 4. Maximum On Channel Leakage Current, Channel to Channel, Test Set- $U_P$ 



\* Includes all probe and jig capacitance. Figure 6. Off Channel Feedthrough Isolation, Test Set-U<sub>P</sub>

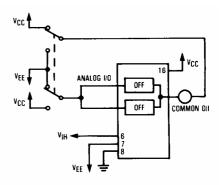
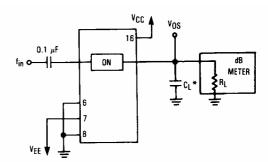
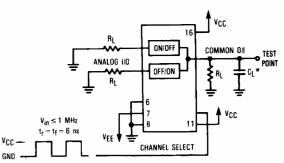


Figure 3. Maximum Off Channel Leakage Current, Common Channel, Test Set-U<sub>P</sub>

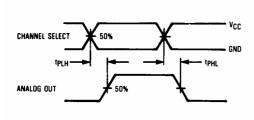


\* Includes all probe and jig capacitance. Figure 5. Maximum On Channel Bandwidth, Test Set-U<sub>P</sub>

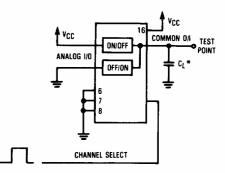


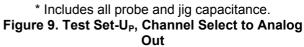
\* Includes all probe and jig capacitance. Figure 7.Feedthrough Noise, Channel Select to Common Out, Test Set-U<sub>P</sub>

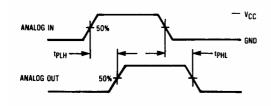












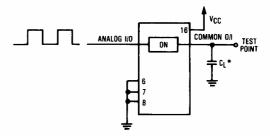


Figure 10. Switching Weveforms

\* Includes all probe and jig capacitance. Figure 11. Test Set-U<sub>P</sub>, Analog In to Analog Out

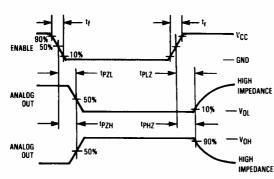


Figure 12. Switching Weveforms

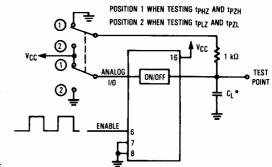


Figure 13. Test Set-U<sub>P</sub>, Enable to Analog Out



